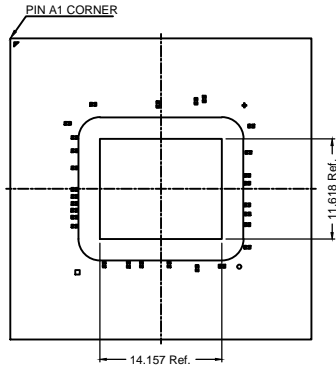
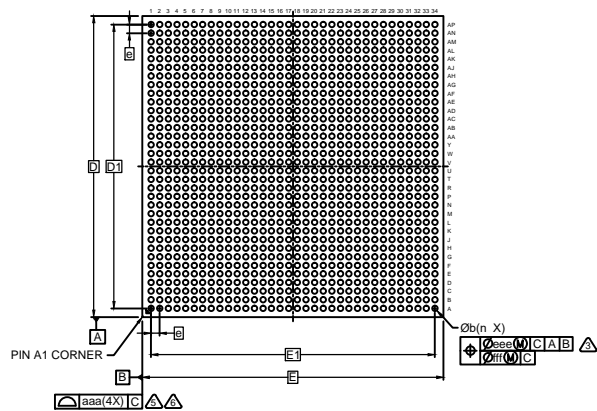
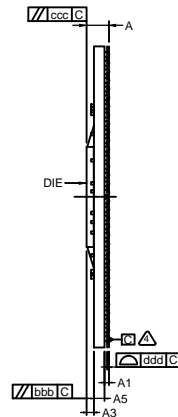




TOP VIEW



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Total Thickness:	A	2.423	2.605	2.787
Stand Off:	A1	0.400	0.500	0.600
Substrate Thickness:	A5	1.258 Ref.		
THICKNESS FROM SUBSTRATE SURFACE TO THE HIGHEST POINT:	A3	0.847 Ref.		
Body Size:	X	E		35.000 BSC.
	Y	D		35.000 BSC.
Ball Diameter:		0.600		
Ball Width:	b	0.500	0.600	0.700
Ball Pitch:	e	1.000		
Ball Count:	n	1156		
Edge Ball Center to Center:	X	E1		33.000
	Y	D1		33.000
Package Edge Tolerance:	aaa	0.200		
Substrate Parallelism:	bbb	0.250		
Top Parallelism:	ccc	0.200		
Coplanarity:	ddd	0.200		
Ball Offset (Package):	eee	0.250		
Ball Offset (Ball):	fff	0.100		

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DR4.14

Title: Package Outline Drawing

Product Family: LAV-AT

Product Name: LAV-AT-70-LFG1156

Pkg Type: FCBGA

Pkg I/O Count: 1156

Pkg Size: 35x35 mm

Document No:

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